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9 bit Level Shifter/Transceiver With 3 State Outputs



ADE-205-039C (Z) 3rd. Edition Jun. 1993

Description

The HD151015 is an IC which consists of 9 bus transceivers (three state output) in a 24 pin package. Signals are transmitter from A to B when the direction control input (DiR) is at a high level, and from B to A when DiR is at a low level. When the enable input (\overline{G}) is high, A and B are isolated. And this product has two terminals (V_{CCA} , V_{CCB}), V_{CCA} is connected with control input and A bus side, V_{CCB} is connected with B bus side. V_{CCA} and V_{CCB} are isolated. Consequently, it is best to change the level in case of two supply voltage coexist on one board and application of power management.

Features

- This product function as level shift transceiver that change V_{CCA} input level to V_{CCB} output level, V_{CCB} input level to VCCA output level by providing different supply voltages to V_{CCA} and V_{CCB}.
- This product is able to the power management : Turn on and off the supply on V_{CCB} side with providing the supply of V_{CCA} .

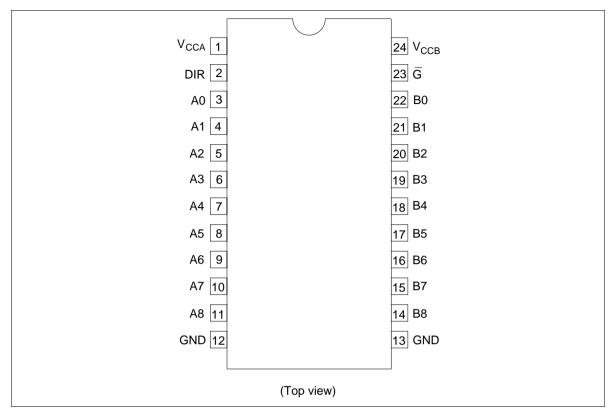
(Enable input (\overline{G}) : High level)

- Inputs and outputs are CMOS level, and the power dissipation is the same as CMOS standard logic.
- Wide operating supply voltage range:

$$V_{CCA} = V_{CCB} = 2 \text{ to } 6 \text{ V} (V_{CCB} \ge V_{CCA} - 0.5 \text{ V})$$

• Wide operating temperature range: Ta = -40 to $85^{\circ}C$

Pin Arrangement



Function Table

Inputs

G	DIR	Outputs
L	L	B data to A bus
L	Н	A data to B bus
Н	X	Z

H: High levelL: Low levelZ: High Imped

Z : High ImpedanceX : Immaterial

Absolute Maximum Ratings

Item	Symbol	Rating	Unit	Conditions
Supply Voltage	V_{CCA}, V_{CCB}	-0.5 to +7.0	V	
Input Diode Current	I _{IK}	-20	mA	$V_1 = -0.5$
		20	mA	$V_{I} = V_{CC} + 0.5$
Input Voltage	V_{IN}	-0.5 to $V_{\rm CC}$ + 0.5	V	
Output Diode Current	I _{OK}	-50	mA	$V_0 = -0.5$
		50	mA	$V_{\rm o} = V_{\rm cc} + 0.5$
Output Voltage	V_{out}	-0.5 to $V_{\rm CC}$ + 0.5	V	
Output Current	I_{o}	±50	mA	
VCC or Ground Current	$I_{\rm CC}$ or $I_{\rm GND}$	±50	mA	per output pin
Storage Temperature	Tstg	-65 to + 150	°C	

Note: 1. The absolute maximum ratings are values which must not individually be exceeded, and furthermore, no two of which may be realized at the same time.

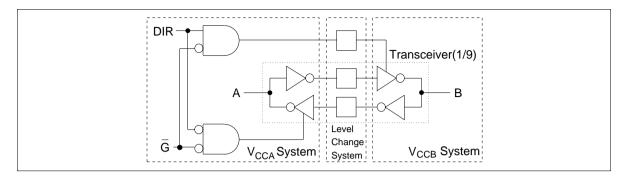
Recommended Operating Conditions

Item	Symbol	Rating	Unit	Conditions
Supply voltage	V _{CCA, B}	2.0 to 6.0	V	$V_{CCB} \ge V_{CCA} - 0.5 \text{ V}$
Input voltage	V _{IN}	0 to V _{cc}	V	
Output voltage	V _{OUT}	0 to V _{cc}	V	
Operating Temperature	T _A	-40 to +85	°C	
Input Rise and Fall Time*1	t _r , t _f	8	ns/V	V _{cc} @3.0 V (Input DiR, \overline{G} , A)
				V _{cc} @4.5 V (Input B)
				V _{cc} @5.5 V (Input B)

Note: 1. The item guarantees maximum limit when one input switches. Waveform: Refer to test circuit of switching characteristics.



Logick Diagram



Electrical Characteristics

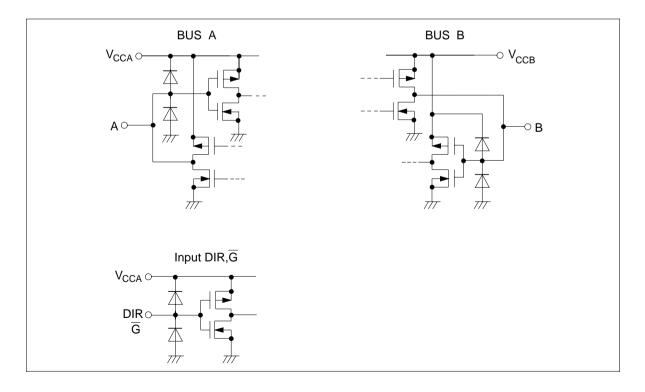
	Sym-	Vcca	Vcce	Ta = 2	:5°C		Ta = - 85°C	-40 to		
Item	bol		(V)	Min	Тур	Max	Min	Max	Unit	Conditions
Input Voltage	V_{IH}	3.0	3.0	2.1	1.5	_	2.1	_	V	$V_{OUT} = 0.1 \text{ V or } V_{CC} - 0.1 \text{ V}$
		4.5	4.5	3.15	2.25	_	3.15	_	_	
		5.5	5.5	3.85	2.75	_	3.85	_	_	
	V_{IL}	3.0	3.0	_	1.5	0.9	_	0.9	V	$V_{OUT} = 0.1 \text{ V or } V_{CC} - 0.1 \text{ V}$
		4.5	4.5	_	2.25	1.35	_	1.35		
		5.5	5.5	_	2.75	1.65	_	1.65		
Output	V_{OH}	2.7	4.5	2.6	2.69	_	2.6	_	V	$V_{IN} = V_{IL}$ or V_{IH} , $I_{OH} = -50 \mu A A^{*1}$
Voltage		2.7	4.5	4.4	4.49	_	4.4	_		$V_{IN} = V_{IL}$ or V_{IH} , $I_{OH} = -50 \ \mu A \ B$
		2.7	4.5	2.3	_	_	2.2	_	V	$V_{IN} = I_{OH} = -4 \text{ mA} A$
		2.7	4.5	3.9	_	_	3.8	_		V_{IL} or V_{IH} $I_{OH} = -12 \text{ mA B}$
	V_{OL}	2.7	4.5	_	0.001	0.1	_	0.1	V	$V_{IN} = V_{IL}$ or V_{IH} , $I_{OL} = 50 \mu A$ A.B
		2.7	4.5	_	_	0.32	_	0.37	V	$V_{IN} = V_{IL}$ or V_{IH} , $I_{OL} = 12$ mA A.B
Input Current	$I_{\rm IN}$	3.3	5.5	_	_	±0.1	_	±1.0	μΑ	$V_{IN} = V_{CC}$ or GND
Off State Output Current	I _{oz}	3.3	5.5	_	_	±0.5	_	±5.0	μА	$V_{IN}(\overline{G}) = V_{IH}, V_{IN} = V_{CC} \text{ or GND},$ $V_{OUT} = V_{CC} \text{ or GND}$
Supply	$I_{\text{CCA.B}}$	3.3	5.5	_	_	8.0	_	80	μΑ	$V_{IN} = V_{CC}$ or GND
Current	I _{CCA}	5.5	0			8.0		80	μΑ	$V_{IN} = V_{CC}$ or GND, B Input OPEN

Note: 1. A: Output A, B: Output B, A.B: Output A.B

Switching Characteristics

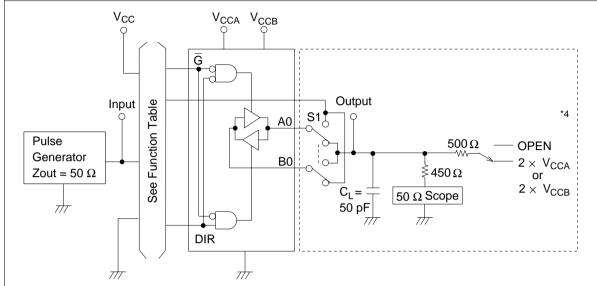
Item	Symbol	Min	Тур	Max	Min	Max	Unit	Conditions
Propagation Delay Time	e t _{PLH}	1.0	5.0	10.0	1.0	12.0	ns	$B \to A$
		1.0	5.0	10.0	1.0	12.0		$A \rightarrow B$
	t _{PHL}	1.0	5.0	10.0	1.0	12.0	ns	$B \to A$
		1.0	5.0	10.0	1.0	12.0		$A \rightarrow B$
Output Enable Time	t _{zH}	1.0	8.0	16.0	1.0	20.0	ns	$\overline{G} \to A$
		1.0	8.0	16.0	1.0	20.0		$\overline{\overline{G}} \to B$
	t _{ZL}	1.0	9.0	16.0	1.0	20.0	ns	$\overline{G} \to A$
		1.0	9.0	16.0	1.0	20.0		$\overline{G} \to A$
Output Disable Time	t _{HZ}	1.0	9.0	16.0	1.0	20.0	ns	$\overline{G} \to A$
		1.0	9.0	16.0	1.0	20.0		$\overline{G} \to B$
	t _{LZ}	1.0	8.0	16.0	1.0	20.0	ns	$\overline{G} \to A$
		1.0	8.0	16.0	1.0	20.0		$\overline{G} \to B$

Input and Output Equivalent Circuit



Switching Time Test Method

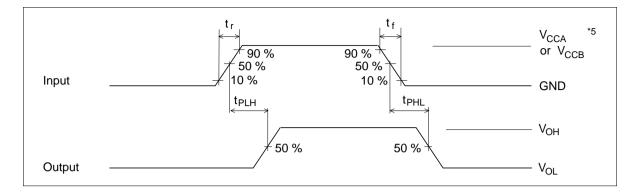
Test Circuit



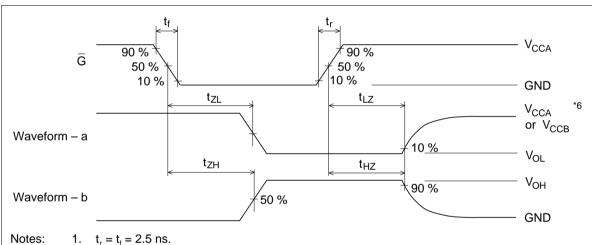
Notes:

- 1. C_L includes probe and jig capacitance.
- 2. A1-B1, A2-B2, A3-B3, A4-B4, A5-B5, A6-B6, A7-B7, A8-B8 are identical to above circuit.
- 3. S1 is a input/output switch.
- 4. When A \rightarrow B: 2 \times V_{CCB}, B \rightarrow A: 2 \times V_{CCA}

Waveforms-1



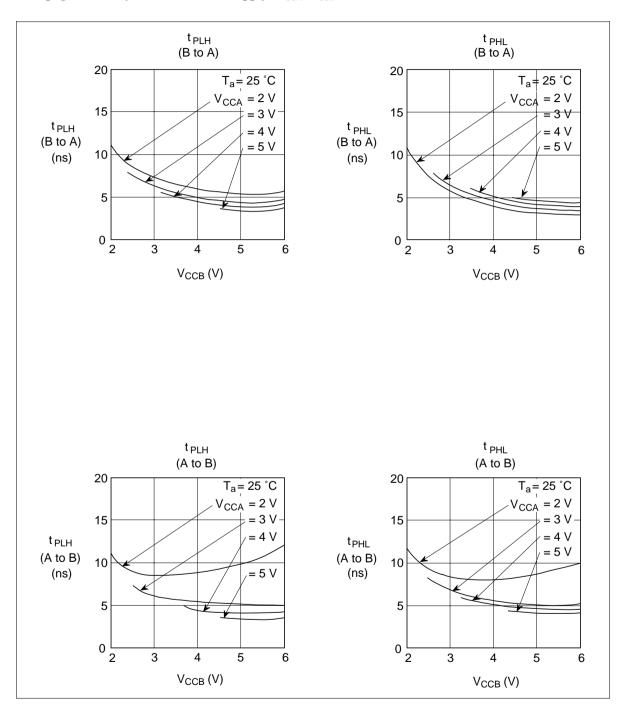
Waveforms-2



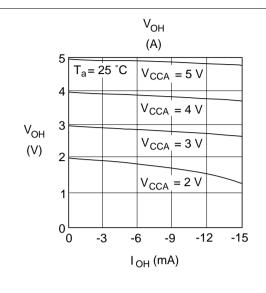
- Input Waveform: PRR = 1 MHz, duty cycle 50%
- Waveform-a is set as outputs are "Low" when enable input is "Low".
- Waveform-b is set as outputs are "High" when enable input is "Low".
- When ${\rm A} \rightarrow {\rm B}{:}\ {\rm V}_{\rm \tiny CCA},\, {\rm B} \rightarrow {\rm A}{:}{\rm V}_{\rm \tiny CCB}$
- When $\overline{G} \to A$: V_{CCA} , $\overline{G} \to B$: V_{CCB}

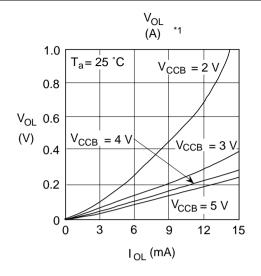
Typical Characteristic Curves

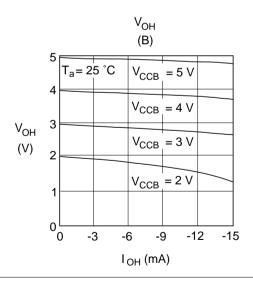
Propagation Delay Times vs Power Supply (V_{CCA}, V_{CCB})

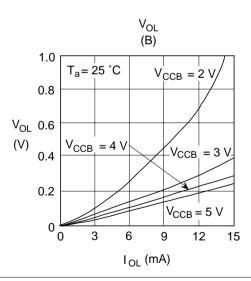


Output Voltage vs Output Current



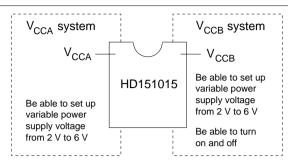






Application

For power management system (1)



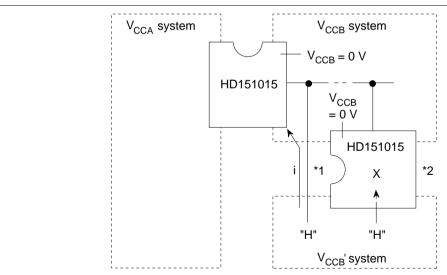
Note: HD151015 is also used for power management system. We show some Examples.

- 1. For V_{CCA} side

 Be able to switch fast mode ($V_{CCA} = 5 \text{ V}$) and power save mode ($V_{CCA} = 3 \text{ V}$)
- 2. For V_{CCB} side

 Be able to switch normal mode ($V_{CCB} = 5 \text{ V}$) and suspend mode ($V_{CCB} = 0 \text{ V}$)
- 3. For both side Be able to switch fast mode ($V_{CCA} = 5 \text{ V}$) and power save mode ($V_{CCA} = 3 \text{ V}$) (When $V_{CCA} = V_{CCB}$, in this case, please switch V_{CCA} and V_{CCB} simulteneously.)

For power management system (2) (Common bus line in different power system)



HD151015 uses conventional CMOS input circuit. So, you have to care of designing in case of common bus line in different power block. We show one example.

In this case, if V_{CCB} become turn off, current flows from bus line to V_{CCB}. (refer to *1)

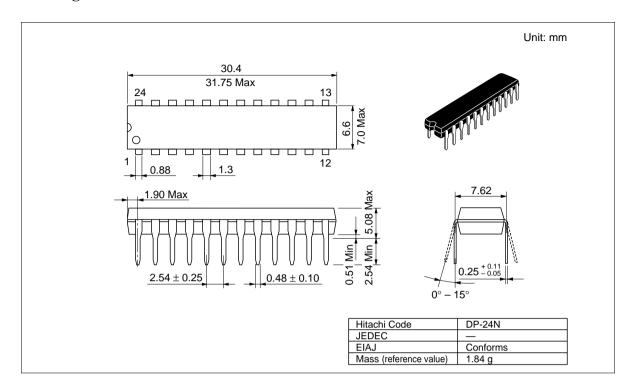
This is cause of malfunction. In order to prevent this problem, I recommend using this device for interface to each power block. (refer to *2)

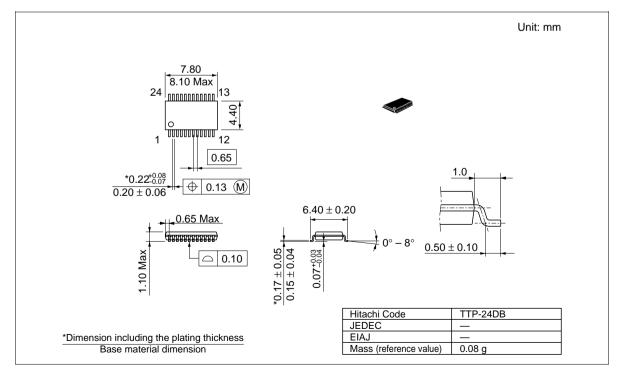
[Cautions on using]

Please use this IC on condition of V_{CCA} usually ON, because if you use it on condition of V_{CCA} being OFF, V_{CCB} being ON, it will be troubled.



Package Dimensions





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For further information write to:

Hitachi Semiconductor (America) Inc. 179 East Tasman Drive, San Jose, CA 95134 Tel: <1> (408) 433-1990 Germany Fax: <1>(408) 433-0223 Tel: <49> (89) 9 9180-0

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Berkshire SL6 8YA, United Kingdom Tel: <886>-(2)-2718-3666 Tel: <44> (1628) 585000 Fax: <44> (1628) 585160

Hitachi Asia Ltd. Hitachi Tower 16 Collyer Quay #20-00, Singapore 049318 Tel: <65>-538-6533/538-8577 Fax: <65>-538-6933/538-3877 URL: http://www.hitachi.com.sg

Hitachi Asia Ltd. (Taipei Branch Office) 4/F, No. 167, Tun Hwa North Road, Hung-Kuo Building, Taipei (105), Taiwan

Fax: <886>-(2)-2718-8180 Telex: 23222 HAS-TP URL: http://www.hitachi.com.tw Hitachi Asia (Hong Kong) Ltd. Group III (Electronic Components) 7/F., North Tower, World Finance Centre, Harbour City, Canton Road Tsim Sha Tsui, Kowloon, Hong Kong

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